503232722 03/24/2015

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT3279340

SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
SEQUENCE:	1	
CONVEYING PARTY DATA		
	Name	Execution Date
GENERAL ELECTRIC COMPANY		12/18/2013

RECEIVING PARTY DATA

Name:	AMPHENOL CORPORATION	
Street Address:	358 HALL AVENUE	
City:	WALLINGFORD	
State/Country:	CONNECTICUT	
Postal Code:	06492	

PROPERTY NUMBERS Total: 13

Property Type	Number
Application Number:	14086267
Application Number:	14053199
Application Number:	29476159
Application Number:	14053212
Application Number:	14150019
Application Number:	14077034
Application Number:	29472322
Application Number:	29472327
Application Number:	14077008
Application Number:	14192844
Application Number:	61969430
Application Number:	14086259
PCT Number:	US2015012707

CORRESPONDENCE DATA

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(202)772-5858

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ATTORNEY DOCKET NUMBER:		143210.01492
NAME OF SUBMITTER:		PETER S. WEISSMAN
SIGNATURE:		/Peter S. Weissman/
DATE SIGNED:		03/24/2015
Total Attachments: 8 source=Assignment1#page1.tif source=Assignment1#page2.tif source=Assignment1#page3.tif source=Assignment1#page4.tif source=Assignment1#page5.tif source=Assignment1#page6.tif source=Assignment1#page7.tif source=Assignment1#page8.tif		

PATENT ASSIGNMENT NUNC PRO TUNC

This Patent Assignment ("Assignment"), effective as of December, 18, 2013 nunc pro tunc (the "Effective Date"), is made by and between GENERAL ELECTRIC COMPANY having a place of business at One River Road, Schenectady, NY 12345 ("Assignor") and AMPHENOL CORPORATION, having a place of business at 358 Hall Avenue, Wallingford, CT 06492 ("Assignee"). This Assignment is made pursuant to and in confirmation of the assignments of patent rights as set forth in the STOCK AND ASSET PURCHASE AGREEMENT, dated as November 7, 2013, by and between General Electric Company and Assignee (the "Stock and Asset Purchase Agreement") and the associated BILL OF SALE, ASSIGNMENT AND ASSUMPTION AGREEMENT, dated as November 7, 2013 (the "Bill of Sale"), by and among the Asset Sellers, as defined in the Stock and Asset Purchase Agreement, the Asset Sellers and Assignee.

WHEREAS, Assignor delivers this Assignment to Assignee pursuant to the Stock and Asset Purchase Agreement and the Bill of Sale.

NOW, THEREFORE, effective as of the Effective Date, and for the consideration set forth in the Stock and Asset Purchase Agreement and for other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, the parties agree as follows:

1. Assignor hereby irrevocably grants, sells, assigns, transfers, conveys and delivers, free of all encumbrances, to, and as applicable confirms the irrevocable sale, assignment, transfer, conveyance and delivery, free of all encumbrances, to Assignee, and Assignee agrees to accept, all of Assignor's rights, title and interest in and to the patents and patent applications as attached hereto as <u>Schedule A</u> ("the Assigned Patents and Applications"), the inventions disclosed therein, and all embodiments owned by Assignor in the United States and worldwide, including:

- all original, reissued, and re-examined letters patents, and renewals and extensions thereof, that originate therefrom in the United States and in foreign countries; and
- all rights to apply, all rights of priority, all continuation, divisional and continuation-in- part that may be filed therefor in the United States and in foreign countries; and
- c. all original, reissued, and re-examined letters patents, and renewals and extensions thereof, that may issue from said continuation, divisional, continuation-in-part and substitute applications; and
- d. all present and future causes of action, the right to enforce any and all rights in the Assigned Patents and Applications, the invention disclosed therein, any continuation, divisional, continuation-in-part; substitute patent application, reissued and/or reexamined letters patent, through either legal or administrative proceedings for past and future damages of any sort; the rights to all income derived from the Assigned Patents and Applications and/or the inventions disclosed therein, including the right to all unpaid royalties with respect to the use of the Assigned Patents and Applications and/or the inventions disclosed therein; and any and all interests, claims, and rights for damages, royalties,

profits, settlements, and other awards by reason of any past, present or future infringement, and all other related causes of action, and the right to sue therefor, for Assignee's own use and behalf and for the use and behalf of its Affiliates, successors and assigns or other legal representatives.

2. The Assigned Patents and Applications and the inventions disclosed therein are to be held and enjoyed by Assignee, its successors and assigns, as fully and entirely as the same would have been held and enjoyed by Assignor if this Assignment had not been made.

3. Assignor hereby authorizes the United States Patent and Trademark Office and any other governmental agencies having jurisdiction over the Assigned Patents and Applications to identify Assignee as the owner of all letters patents issuing from any applications pending related to the Assigned Patents and Applications. Assignor further hereby authorizes the United States Patent and Trademark Office and any patent office in any and all foreign countries to issue any and all patents related to the Assigned Patents and Applications, including any and all Certificates of Correction, to Assignee as the assignee of Assignor's entire right, title and interest in and to the same, for the sole use and behalf of Assignee, its successors, assigns, and/ or legal representatives, from now through the full end of the term for which any additional patents may be granted.

4. Any and all disputes or causes of action between Assignor and Assignee arising under this Assignment shall be governed by the dispute resolution provisions set forth in Section 12.11 of the Stock and Asset Purchase Agreement.

5. Except as expressly provided in the Stock and Asset Purchase Agreement, Assignor makes no warranties, express or implied, with respect to the Assigned Patents and Applications.

6. This Assignment may be executed in one or more counterparts, each of which when executed shall be deemed to be an original but all of which taken together shall constitute one and the same agreement. Delivery of an executed counterpart of a signature page to this Assignment by electronic mail or facsimile shall be as effective as delivery of a manually executed counterpart of this Assignment.

7. No provision of this Assignment may be amended, supplemented or modified except by a written instrument making specific reference hereto signed by all the parties.

[NEXT PAGE]

IN WITNESS WHEREOF, the parties have caused this Patent Assignment to be executed as of the date first written above by its duly authorized officer.

ASSIGNOR:

Date: March 18 2015

GENERAL ELECTRIC OMPANY By: Name: 14 hael e ad Title: test counsel ЪЯ

ASSIGNEE:

AMPHENOL CORPORATION

Date: MHACH 19, 2015

By: Edward C. Wetmos

Name: Edward C. Wetmore Title: Vice President, Secretary and General Counsel

SCHEDULE A

Ref. No.	App. No.	Pat. No.	Country	Title
134166-5	2006-539502	5290521	JP	Gas sensor device
135315-11	2008-535885	4477143	JP	Single crystal silicon sensor with high aspect ratio and curvilinear structures and associated method
138981	2001-7002836		KR	Proportional micromechanical device
138981	2000-569132	4831446	JP	Proportional micromechanical device
151150-3	2005-028526	4871513	JP	Micromechanical device with thinned cantilever structure and related methods
151150	05250525.2		EP	Micromechanical device with thinned cantilever structure and related methods
170595	• •	10-1296031	KR	Pressure sensors and methods of making the same
170595-6	2008-52809 1	5342236	JP	Pressure sensors and methods of making the same
181222-5	06800501.6	1935039	EP	Unique 4.26 um resonant cavity light emitting diode
181222-6	1103/DELNP/2008		IN	Unique 4.26 um resonant cavity light emitting diode
181222-7	2008-526956	5357542	JP	Mid-infrared resonant cavity light emitting diodes
185537	1020037014102		KR	Automatic calibration mode for carbon dioxide sensor
222275	al ar	10-1321169	KR	Temperature sensor
222275-5	2007-325419	5041999	JP	Temperature sensor
238472-4	2011-195530	5351943	JP	Device for use as dual-sided sensor package
240804-5	2010-291906	5134679	JP	Snap-fit sensor assembly
241065-6	2012-530882	5352011	JP	Method and system for compensating for variation in attenuation measurements caused by changes in ambient temperature
225622-4	2008-320385	**	JP	Gas sensor and method of making
228142-4	2008-321832	*	JP	Gas sensor and method of making
231260-6	2011-511672		JP	Catheter tip device and method for manufacturing same
238205	2010-0132635		KR	Device for measuring fluid properties in caustic environments

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Ref. No.	App. No.	Pat. No.	Country	Title
238205-6	2010-283947		IP	Device for measuring fluid
230203-0	2010-283947		Jr	properties in caustic environments
239302	2012-7005314	~3	KR	Antenna assembly
239302-5	2012-522835	<u>المحمد المحمد المحمد</u>	JP	Antenna assembly
240923-4	2011-163775	GIG	JP	Scaled enclosure and system
	<u> </u>			Method and system for
241065		10-1280190	KR	compensating for variation in
241000		10-1200190	AR	attenuation measurements caused
				by changes in ambient temperature
·				Method for fabricating a
241230-5	2010-289963	Gente	JP	microelectromechanical sensor
				with a piezoresistive type readout
241351-6	2011-131721		JP	Sensor and method for fabricating
241331-0	2011-131/21		Jr	the same
241351-11	2011-130778		JP	Elongated catheter tip pressure
241331-11	2011-130/78	~~	Jr	sensor with backside vent
242894	2011-0135385		KR	Method for fabricating a sensor
242894-5	2011-273829	~~~	JP	Method for fabricating a sensor
				Device for measuring
243599-5	2012-115672		JP	environmental forces and method
				of fabricating the same
243701-5	2012-113925		JP	Method and device for preventing
243701~3	2012-113923		31	corrosion on sensors
244122-4	2012-033481		JP	Catheter tip device and method for
244122=4	2012-035401		91	manufacturing same
245281	2013-7013017		KR	Device for measuring properties of
24,5201	2013-7013017		٨ĸ	working fluids
245281	2013-540111		JP	Device for measuring properties of
243201	2013-340111		Jr	working fluids
247491-5	2012-156068		JP	Heating system, heater, and
247471-0	2012-130000		J.C.	methods of heating a component
250172-4	2013-219909		JP	Device and method for measuring
230172-7	2012-227707		54	moisture content
250172	201310507240.6		CN	Device and method for measuring
230172	201310307240.0		CN	moisture content
250172	14111284.6		НК	Device and method for measuring
250172	14111204.0		UV	moisture content
252202-4	2012-258069	84	JP	Pressure sensor assembly
256 203	2014-7027631		KR	Flexible cable for low profile
230203	2017-1021031		nn.	electrical device
				Sensor assembly with protective
257869	2013-0067359		KR	coating and method of applying
				same

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Ref. No.	App. No.	Pat. No.	Country	Title
		**************************************	1	Sensor assembly with protective
257869-4	2013-121393	~~	JP	coating and method of applying
				same
261568	2013-0069685		KR	Non-dispersive infrared sensor
201306	2013-0009063			with a reflective diffuser
261568-7	2013-125112		JP	Non-dispersive infrared sensor
201308-7	2013-123112		JI	with a reflective diffuser
262412-1	61871370	20 F.	US	Modular pressure sensing unit
269207-1	201310461274.6		CN	High sensitivity turbidity sensor
207207-1	2013104012/4.0	***		with light pipe
270300	PCT/IB2014/001503		РСТ	Light Sensor Assembly and
270500	rc1/102014/001505	~~~	ru	Vehicle Incorporating the Same
270300-1	201310347193.3		CN	Light sensor assembly and vehicle
270300-1	201510547195.5		CIN	incorporating the same
270763-1	14/086259		US	Semiconductor sensor chips
270763A-1	14/086267		US	Semiconductor sensor chips
270763	PCT/US14/66604	@r.	wo	Semiconductor sensor chips
		~~~~~		Heater assembly with protective
271091-1	14/053199	A	US	coating and method of applying
				same
		*****		Heater assembly with protective
271091	14188464.3		EP	coating and method of applying
				same
				Heater assembly with protective
271091	201410539629.3	~~	CN	coating and method of applying
				same
				Heater assembly with protective
271091	MX/A/2014/012369	10°10	MX	coating and method of applying
			·	same
				Heater assembly with protective
271091	2014-0138329	# <b>~</b>	KR	coating and method of applying
				same
271282-1	29/476159		US	Handheld meter
				Electrical lead frame with
271571-1	14/053212	ac-01	US	protective coating and method of
				applying same
				Electrical lead frame with
271571	14188465.0		EP	protective coating and method of
**************				applying same
		,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,		Electrical lead frame with
271571	201410540117.9	<b>66 76</b> .	CN	protective coating and method of
				applying same

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Ref. No.	App. No.	Pat. No.	Country	Title
*********				Electrical lead frame with
271571	MX/A/2014/012370		MX	protective coating and method of
				applying same
	1	***************************************	1	Electrical lead frame with
271571	2014-0138314	#16.073	KR	protective coating and method of
				applying same
		4 <u>20022002700</u> 270077007777777777777777777		Low pressure sensors and flow
271913-1	14/150019	<b>X</b> 020	US	sensors
272768-1	14/077034	e a	US	Optical gas sensor
272768	PCT/US14/65033	ap.	wo	Optical gas sensor
272770-1	29/472322		US	Optical gas sensor
272770A-1	29/472327	49999999999999999999999999999999999999	US	Optical gas sensor
				Upper housing body of an optical
272770	201430555228.8	CELCE.	CN	gas sensor
			1	Lower housing body of an optical
272770	201430555245.1	~~	CN	gas sensor
272770	TBD		IN	Optical gas sensor
272770	TBD	~~~~~	EP	Optical gas sensor
272771-1	14/077008		US	Optical gas sensor
<i>du 1 du 1 1</i> 1 ⁻ 1	19/07/0/0			Highly conductive surface contact
				with temperature sensor data
	14/192844	~~	US	logger. Enhancing temperature
				sensor performance in response
270369				time in all environments
				(atmosphere and vacuum) and
				thermal conductivity with surface
			<u> </u>	being measured.
140688	04785002.9		EP	Surface mount package and method for forming multi-chip
140655				microsensor device
			<u>}</u>	Catheter die and method of
250212	13710165.5		EP	
		<b></b>		fabricating the same
269125-1	61/969,430	000 000	US	Battery cell health monitoring
	auerranna a baile a statistic a sta			using eddy current sensing
269125	PCT/US15/12707		wo	Battery cell health monitoring
				using eddy current sensing
000001	DOWNRICH			Systems and methods for
268951	PCT/US14/63897		wo	temperature compensated flow
			ļ	sensing
A/007 ·	4 1000 4 4 4	tor or	US	Systems and methods for
268951	14/072,234			temperature compensated flow
				sensing
269122	PCT/US14/63904		wo	Systems and methods for flow
an war san sa	A GALGUATION SUT			sensing in a conduit

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Ref. No.	App. No.	Pat. No.	Country	Title
269122	14/072,393		US	Systems and methods for flow sensing in a conduit
265502	PCT/US14/24743	30 Gr	wo	Systems and methods for hybrid flow sensing
270458	TBD (filed 12/16/2013)	<b>NS. TR</b>	India	Docking system
270458	TBD (filed 12/16/2013)	47	РСТ	Docking system
275656		-	US	Low cost flex sensor modular array
275968			US	Battery health monitoring using low profile temperature- insensitive strain sensor

143210 01000/36365191v.2

# PATENT REEL: 035241 FRAME: 0237

RECORDED: 03/24/2015